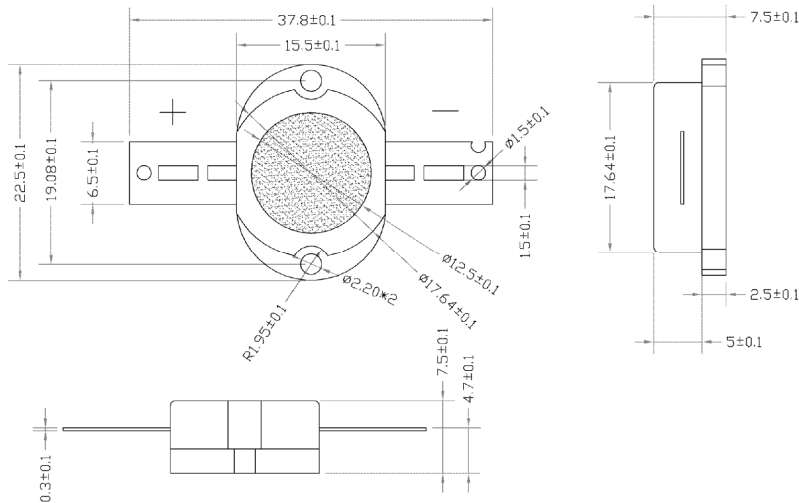


●光源规格 (Light source spec):



Chip brand	芯片品牌	Bridgelux 45mil
Chip quantity	芯片数量	10PCS
Circuit structure	电路结构	3pcs in series and 3pcs in parallel
Gold thread spec	金线规格	Φ 1.2mil Au
Stents material	支架材质	copper 铜材
Net weight	净重	5.5g

●封装尺寸 Package Dimensio



平面尺寸图

Dimension (mm)

1. All dimensions are in millimeters (inches).所有的尺寸均以毫米计(英寸)。
2. Tolerance is ±0.25mm(0.010") unless otherwise noted.宽度是±0.2 毫米(0.010)除非另有注明。
3. Specifications are subject to change without notice.规格如有更改,恕不另行通知。

● **TA = 25°C (Electrical /Optical Characteristics at TA=25°C (电气/光学特性)**

Parameter 参数	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous flux 光通量	φ	900	950	1000	Lm	IF =1000mA
Viewing Angle 视角	2θ1/2	110	120	130	deg	IF =1000mA
Color temperature 色温	TC	5500	6000	6500	K	IF =1000mA
Forward Voltage 正向电压	vF	9.0	10.5	12.0	v	IF =1000mA
Reverse Current 反向电流	IR	0		5	uA	IF =1000mA

● **Absolute Maximum Ratings at TA=25°C (在 TA = 25°C绝对最大额定值)**

Parameter 参数	Maximum Rating 最大额定值
Power Dissipation 功耗	10W
Peak Forward Current(1/10 Duty Cycle, 0.1ms Pulse Width)脉冲峰值电流	1800mA
Continuous Forward Current 直流电流	1000mA
Continuous working current 连续工作电流	850 mA
Derating Linear From 30°C 30°C以上电流线性降低值	0.07mA/°C
Reverse Voltage 反向电压	15V
Operating Temperature Range 工作温度	-20°C to + 80°C
Storage Temperature Range 储存温度	-30°C to + 100°C
Lead Soldering Temperature [1.6mm(.063") From Body] 焊接温度	260°C for 5 Seconds

● 电性特征曲线(Electrical characteristics curve)

Fig1.Relative spectrum power (相对光谱功率)

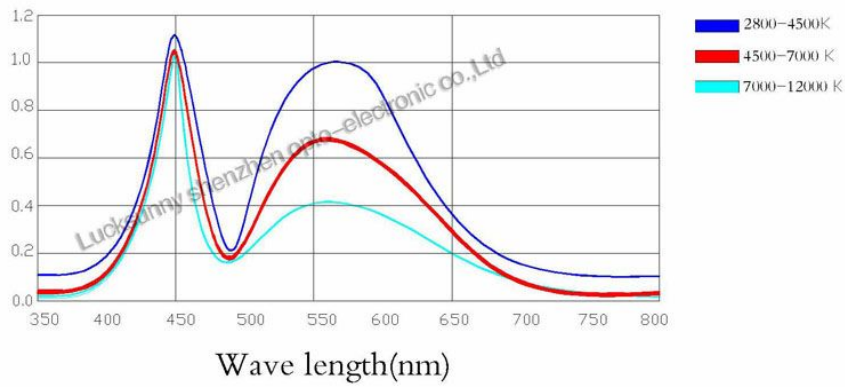


Fig2. Forward Current vs. Forward Voltage  
电压与电流特性曲线

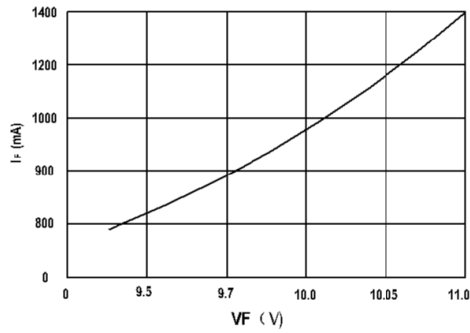


Fig.3Relative Luminous Intensity  
相对光强与电流曲线 vs. Forward Current

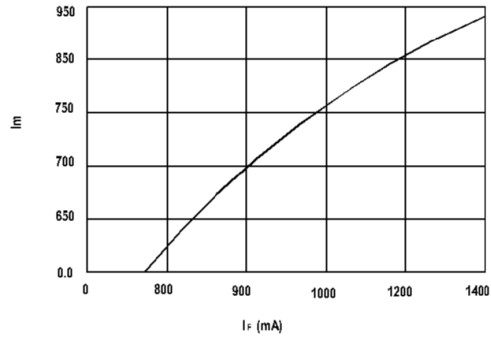


Fig.4 Output flux and junction temperature  
输出光通量与结温

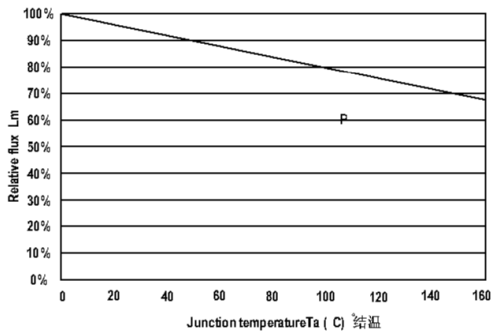


Fig.5 Shine Angle  
发光视角

